

FIG. 1

112 ~

114 ~

Die information is defined.
e.g. die size, pad locations.
Information is stored

116 ~

Netlist is created, defining
substrate connections

118 ~

Routing parameters are
created and stored. e.g.
priority of signals.

120 ~

The above information
collected is stored and then
processed by a machinery
(or software) that will perform
the next placement steps

Go to 124

FIG. 2

122 →

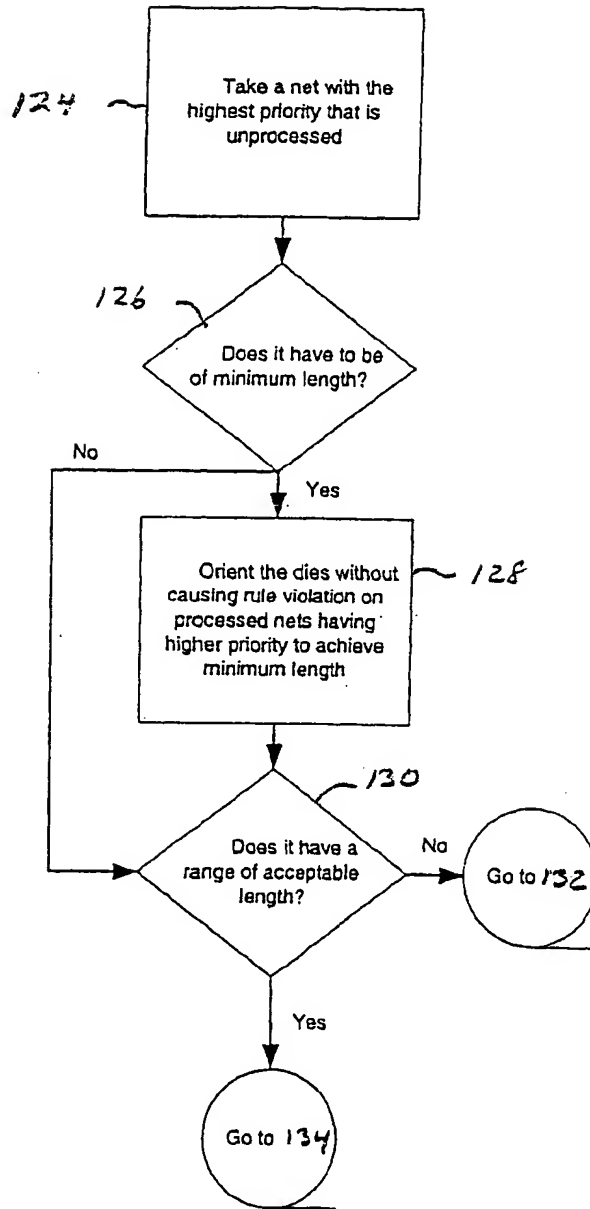


FIG. 3

122 (CONTINUED) ↘

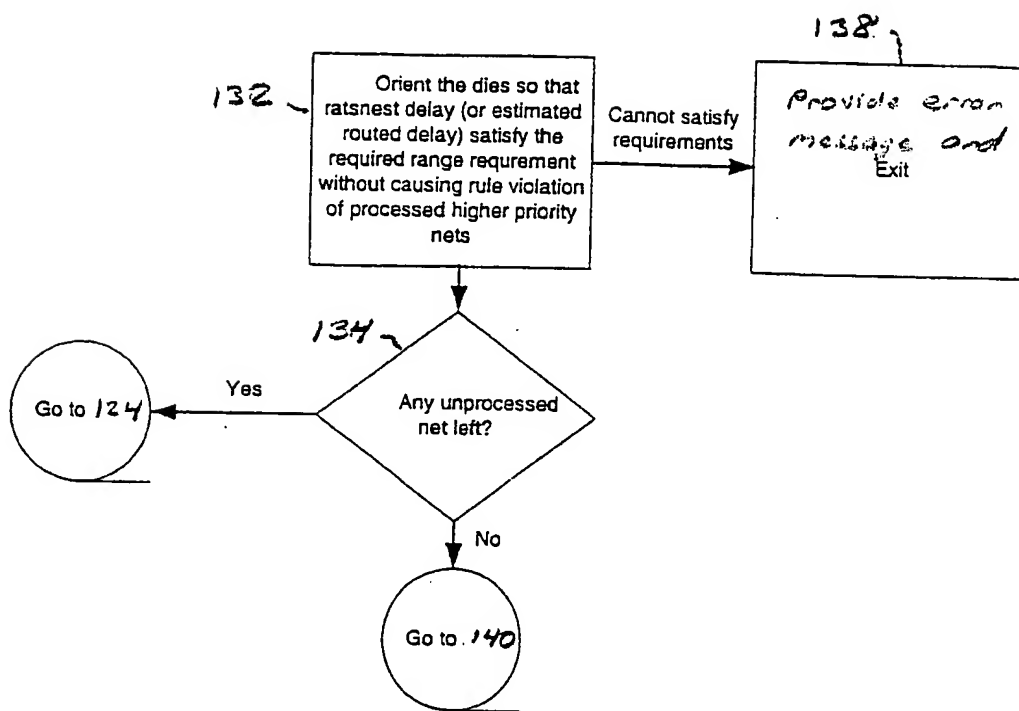


FIG. 4

136

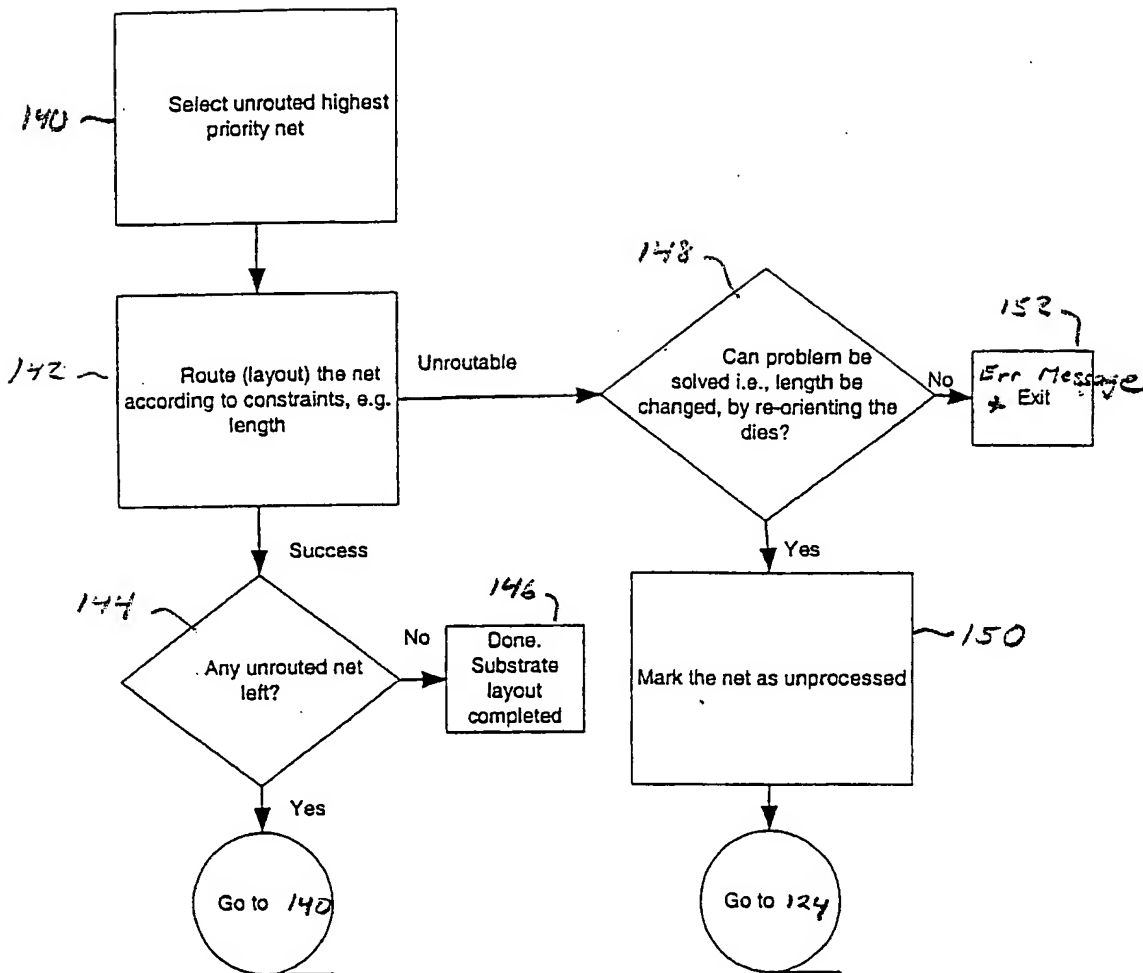


FIG. 5

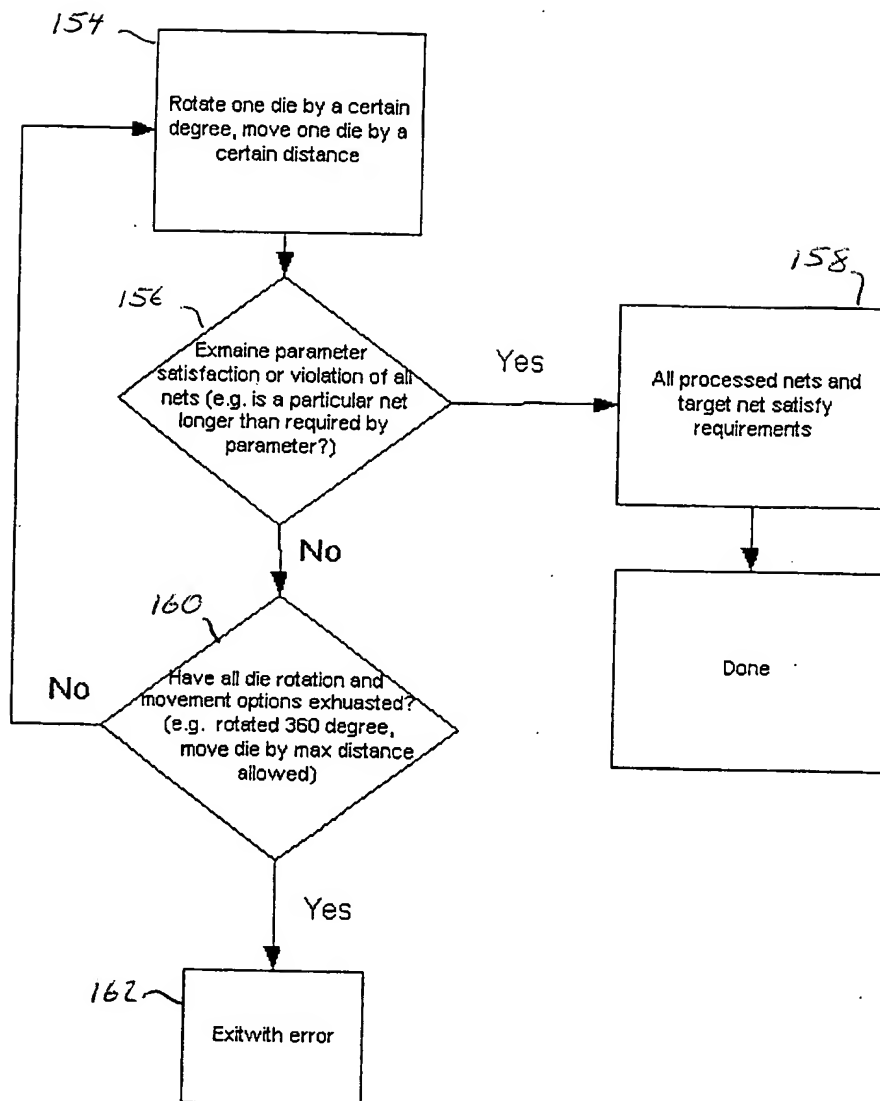


FIG. 6

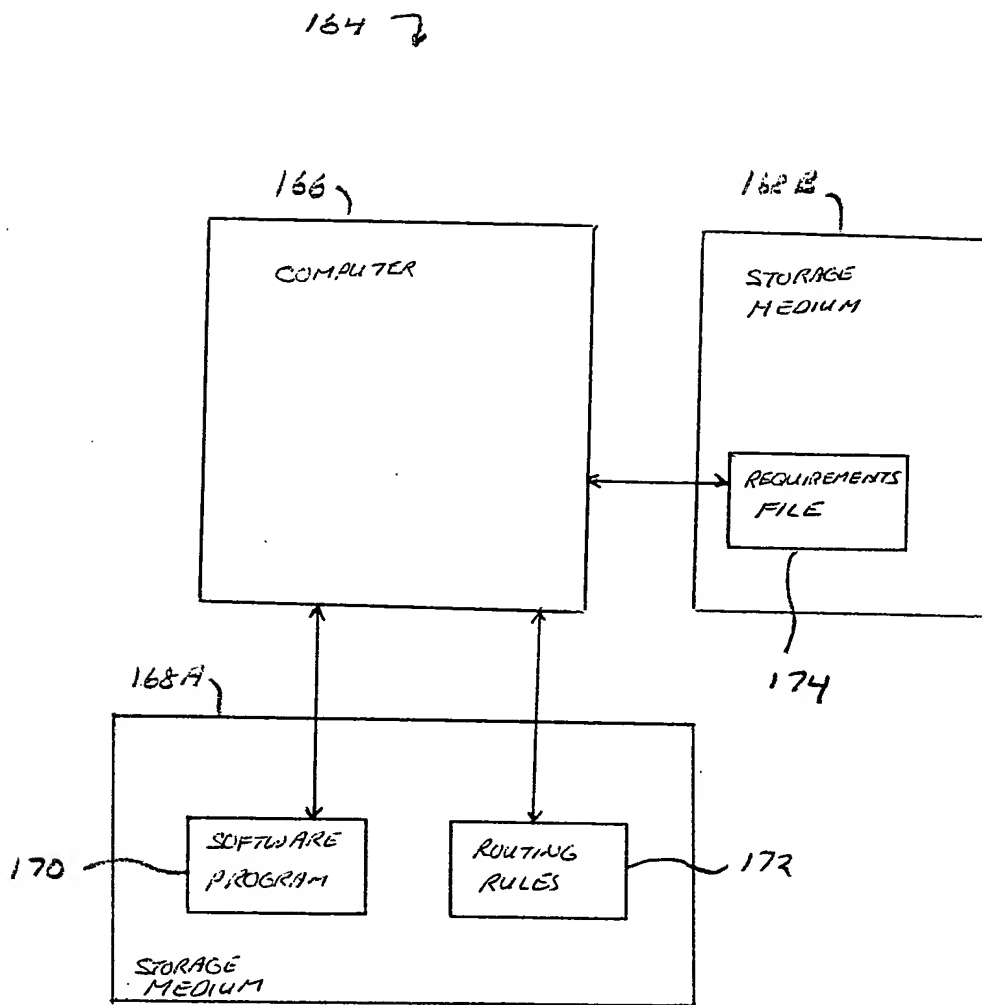


FIG. 7